

Date: 4/17/2021

Material Number: EFR32BG12P232F1024GL125-C

Pkg Config.: PK1295

Detailed Device Composition

No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Mold Compound	36.45	Carbon Black	1333-86-4	0.300	0.109	3000	0.1424	1424
			Epoxy Resin (Proprietary)	Proprietary	7.500	2.734	75000	3.5599	35599
			Phenol Resin (Proprietary)	Proprietary	7.500	2.734	75000	3.5599	35599
			Silicon Dioxide	60676-86-0	84.700	30.872	847000	40.2030	402030
2	Die Attach Epoxy	0.87	2-Ethyl-4-methyl-1H-imidazole-1-propiononitrile	23996-25-0	0.500	0.004	5000	0.0057	57
			Acrylate monomer	Proprietary	7.500	0.065	75000	0.0851	851
			Additive	Proprietary	7.500	0.065	75000	0.0851	851
			Bismaleimide monomer	TS ref# 10049	15.000	0.131	150000	0.1701	1701
			Epoxy Resin	25068-38-6	8.000	0.070	80000	0.0907	907
			Silica (Amorphous) A	60676-86-0	46.000	0.401	460000	0.5218	5218
			Silicon Dioxide	60676-86-0	15.000	0.131	150000	0.1701	1701
			Substituted Silane	Proprietary	0.500	0.004	5000	0.0057	57
3	BGA Ball	12.96	Copper	7440-50-8	0.500	0.065	5000	0.0844	844
			Silver	7440-22-4	1.000	0.130	10000	0.1688	1688
			Tin	7440-31-5	98.500	12.770	985000	16.6290	166290
4	Substrate	20.62	Barium Sulfate	7727-43-7	0.300	0.062	3000	0.0805	805
			Copper	7440-50-8	31.800	6.556	318000	8.5377	85377
			Epoxy Resin (Proprietary)	Proprietary	52.200	10.762	522000	14.0148	140148
			Gold	7440-57-5	0.600	0.124	6000	0.1611	1611
			Nickel	7440-02-0	2.800	0.577	28000	0.7517	7517
			Organic Filler	14807-96-6	0.600	0.124	6000	0.1611	1611
			Organic Solvent	Proprietary	0.500	0.103	5000	0.1342	1342
5	Bond Wire	0.25	Copper	7440-50-8	96.000	0.241	960000	0.3138	3138
			Gold	7440-57-5	1.000	0.003	10000	0.0033	33
			Palladium	7440-05-3	3.000	0.008	30000	0.0098	98

6	Die	5.64	Silicon	7440-21-3	99.800	5.628	998000	7.3286	73286
			Silicon Dioxide	60676-86-0	0.200	0.011	2000	0.0147	147
	Total Unit Weight =	76.79				76.79		100.0000	1000000